



Initial Product/Process Change Notification
Document #: IPCN25523X
Issue Date: 16 August 2023

Title of Change:	SOIC16 EHDLF RPPF Pruning and Migration
Proposed First Ship date:	03 Feb 2025 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or Izel.Rodriguez@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >
Marking of Parts/ Traceability of Change:	Part marking shows assembly date. Assembly lot (marked on reel and shipping boxes) is traceable to Assembly BOM used.
Change Category:	Assembly Change
Change Sub-Category(s):	Material Change
Sites Affected:	
onsemi Sites	External Foundry/Subcon Sites
onsemi Carmona, Philippines	None

Description and Purpose:

Change lead frame from Std RPPF Etched (Flag Size: 70x70mil) to EHDLF RPPF Stamped (Flag Size: 90x130mil).

Note:

This change will use wafer that has been fabricated in Aizu as communicated in IPCN25297X.

This change will use PCC wire on its BOM as communicated in IPCN25463X.

	Before Change Description	After Change Description
LeadFrame	Std RPPF Etched (Flag Size: 70x70mil)	EHDLF RPPF Stamped (Flag Size: 90x130mil)

There is no product marking change as a result of this change.



Initial Product/Process Change Notification
Document #: IPCN25523X
Issue Date: 16 August 2023

Qualification Plan:

QV DEVICE NAME: NCV5700DR2G

RMS: 91678

PACKAGE: SOIC 16L

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	2016 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	1000 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B120		

Estimated date for qualification completion: 24 February 2024

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NCD5702DR2G	NCV5700DR2G
NCD5700DR2G	NCV5700DR2G